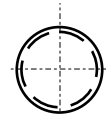
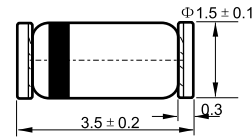



MINI MELF/SOD-80


Dimension in millimeters

Features

- ✧ Surge overload ratings to 2 amperes peak
- ✧ Ideal for printed circuit board
- ✧ Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- ✧ Terminal : Pure tin plated lead free,
- ✧ Mounting position: Any
- ✧ High temperature soldering : 260°C / 10 seconds at terminals
- ✧ Weight: 0.12 gram

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Maximum Ratings

Type Number	Symbol	Value	Units
Repetitive Peak Reverse Voltage	VRRM	100	V
Reverse Voltage	VR	75	V
Forward Repetitive Peak Current (Note 1)	IFRM	500	mA
Forward Continuous Current (Note 1)	IFM	300	mA
Average Forward Current	IF (AV)	150	mA
Peak Forward Surge Current tp=1uS	IFSM	2.0	A
Power Dissipation (Note 1)	Pd	500	mW
Thermal Resistance Junction to Ambient Air (Note 1)	RθJA	350	K/W
Operating and Storage Temperature Range	TJ, TSTG	-65 to + 175	°C

Electrical Characteristics

Type Number	Symbol	Min	Max	Units
Forward Voltage IF=5.0mA IF= 50mA	VF	0.62 -	0.72 1.0	V
Peak Reverse Current VR=20V VR=20V, Tj=150°C VR=75V	IR	-	25 50 5	nA uA uA
Junction Capacitance VR=0, f=1.0MHz	Cj	-	4.0	pF
Reverse Recovery Time (Note 2)	trr	-	4.0	nS

- Notes:
1. Valid Provided that Terminals are Kept at Ambient Temperature.
 2. Reverse Recovery Test Conditions: IF=10mA, VR=6V, Irr=0.1 x IR, RL=100Ω.

RATINGS AND CHARACTERISTIC CURVES (LL4148)

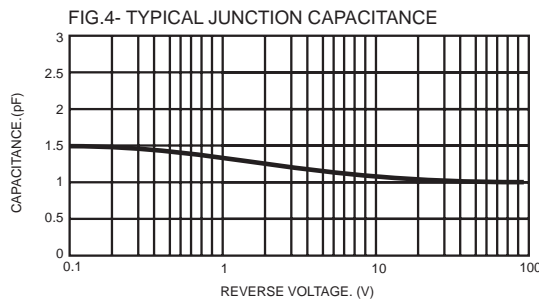
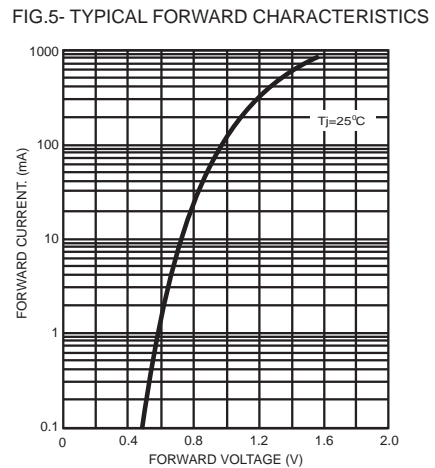
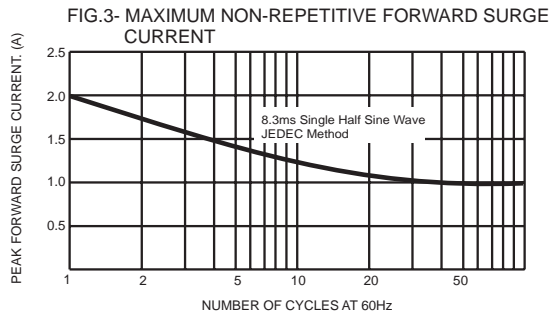
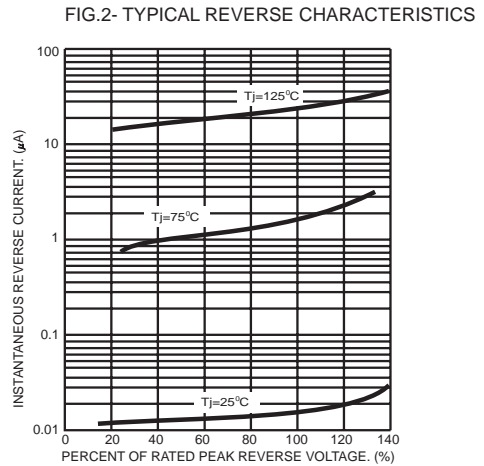
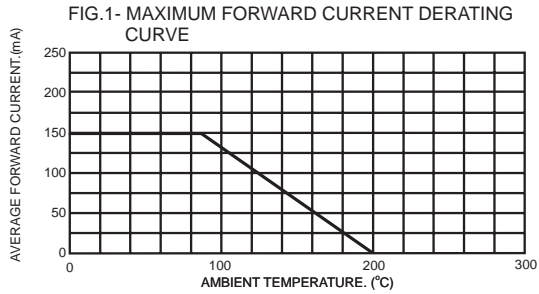
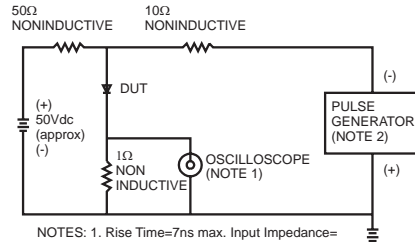


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



NOTES: 1. Rise Time=7ns max. Input Impedance= 1 megohm 22pf
2. Rise Time=10ns max. Source Impedance= 50 ohms

